Zener Diode

DE2S08200L

Panasonic

DE2S08200L

Silicon epitaxial planar type

For ESD protection

■ Features

- High ESD
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)
- Marking Symbol: FC

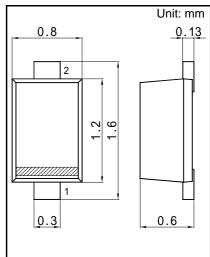
Packaging

Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

■ Absolute Maximum Ratings Ta = 25 °C

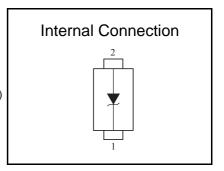
Parameter	Symbol	Rating	Unit			
Total power dissipation *1	PT	150	mW			
Electrostatic discharge *2	ESD	±30	kV			
Junction temperature	Tj	150	°C			
Operating ambient temperature	Topr	-40 to +85	°C			
Storage temperature	Tstg	-55 to +150	°C			
**						

Note) *1: Mounted on glass epoxy print board. (45 mm x 45 mm x 1 mm) Solder in (0.8 mm x 0.6 mm)



- 1. Cathode
- 2. Anode

Panasonic	SSMini2-F5-B
JEITA	SC-79
Code	SOD-523



■ Electrical Characteristics Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Zener voltage *1,*2	VZ	IZ = 1 mA	7.79		8.61	V
Reverse current	IR	VR = 5 V			0.5	μA
Terminal capacitance	Ct	VR = 0 V, f = 1 MHz		43		pF
Temperature coefficient of zener voltage *3	SZ	IZ = 1 mA		4.5		mV/°C

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.

- *1: The temperature must be controlled 25°C for VZ mesurement.
 VZ value measured at other temperature must be adjusted to VZ (25°C)
 - *2: VZ guaranted 20 ms after current flow.
 - *3: Tj = 25° C to 150° C

Established: 2012-10-24

: 2013-11-01

Revised

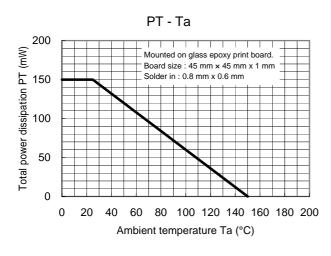
^{*2:} Test method:IEC61000_4_2(C = 150 pF,R = 330 Ω , Contact discharge:10 times)

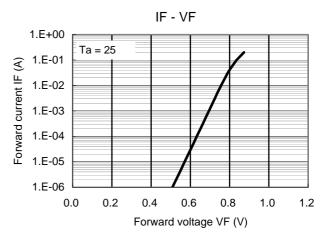
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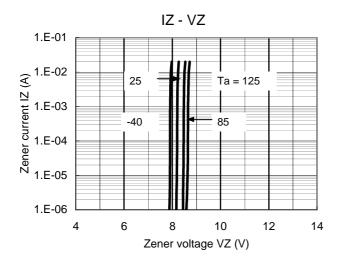
Zener Diode

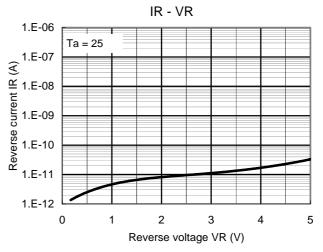
DE2S08200L

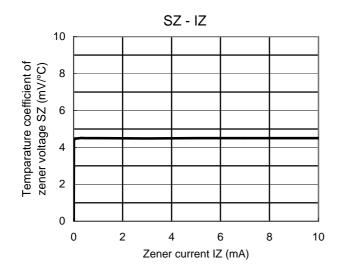
Technical Data (reference)

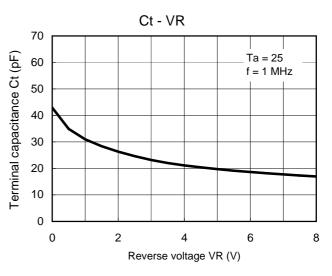












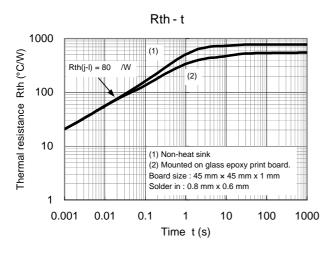
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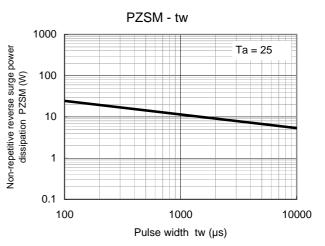
Established: 2012-10-24 Revised: 2013-11-01 **Panasonic**

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DE2S08200L

Technical Data (reference)





Established: 2012-10-24 Revised: 2013-11-01

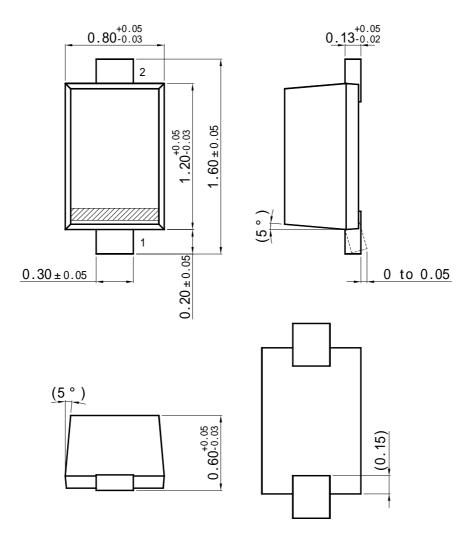
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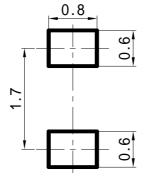
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SSMini2-F5-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



Established: 2012-10-24 Revised: 2013-11-01

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